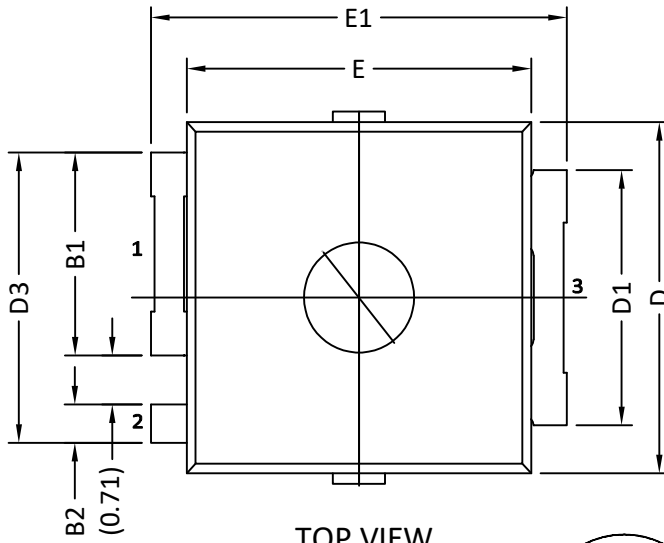
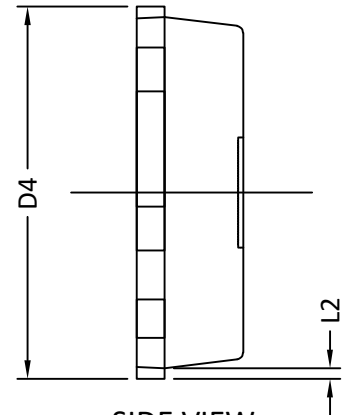




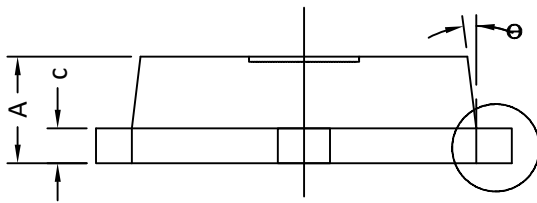
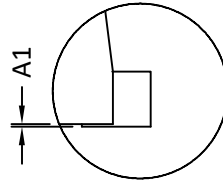
UltraSO-8™ PACKAGE OUTLINE



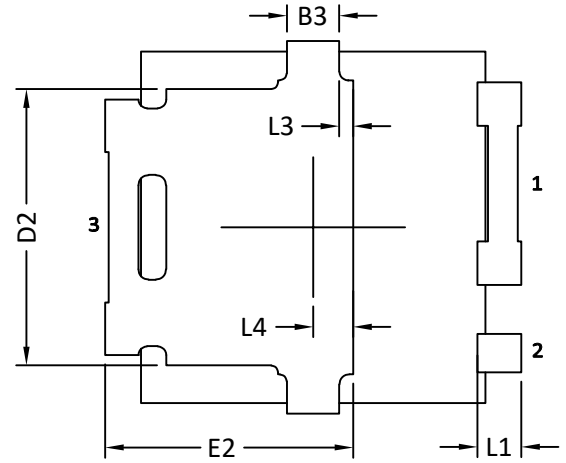
TOP VIEW



SIDE VIEW

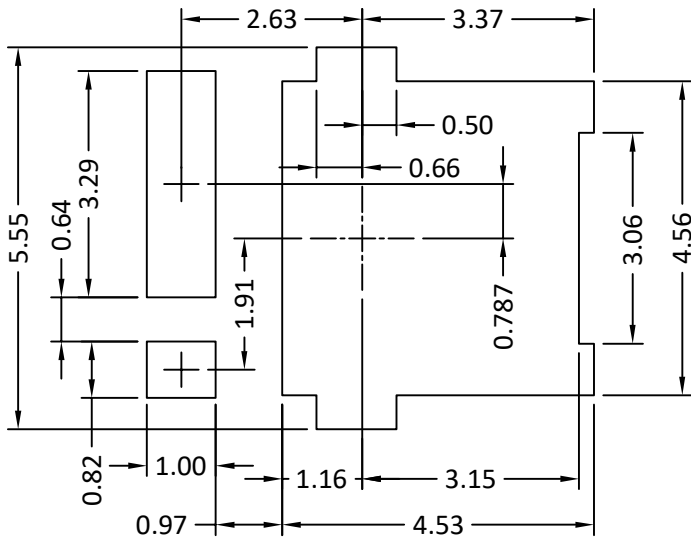


SIDE VIEW



BOTTOM VIEW

RECOMMENDED LAND PATTERN



UNIT: mm

SYMBOLS	DIM. IN MM			DIM. IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.450	1.650	1.700	0.057	0.065	0.067
A1	0.000	---	0.050	0.000	---	0.002
B1	2.700	2.950	3.150		0.116	0.124
B2	0.450	0.560	0.650	0.018	0.022	0.026
B3	0.550	0.600	0.650	0.022	0.024	0.026
c	0.450	0.510	0.560	0.018	0.020	0.022
D	5.000	5.110	5.300	0.197	0.201	0.209
D1	3.550	3.710	4.300	0.140	0.146	0.169
D2	3.600	4.010	4.300	0.142	0.158	0.169
D3	4.000	4.220	4.300	0.157	0.166	0.169
D4	5.110	5.410	5.500	0.201	0.213	0.217
E	4.900	5.000	5.100	0.193	0.197	0.201
E1	5.900	6.050	6.200	0.232	0.238	0.244
E2	3.500	3.610	3.800	0.138	0.142	0.150
L1	0.500	0.640	1.000	0.020	0.025	0.039
L2	0.000	---	0.100	0.000	---	0.004
L3	0.270	0.320	0.370	0.011	0.013	0.015
L4	0.570	0.620	0.670	0.022	0.024	0.026
e	0.00	---	10°	0.000	---	10°

NOTE

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
2. CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
3. THIS PACKAGE WAS QUALIFIED USING IR REFLOW PROCESS (JEDEC STANDARD). FOR USAGE IN OTHER SOLDERING PROCESSES, PLEASE CONTACT LOCAL AOS REPRESENTATIVES.